

DMEG 250

250 Watts, 50 Volts, Pulsed Avionics 960 - 1215 MHz

GENERAL DESCRIPTION

The DMEG 250 is a high power COMMON BASE bipolar transistor. It is designed for pulsed systems in the frequency band 960-1215 MHz. The device has gold thin-film metallization for proven highest MTTF. The transistor includes input and output prematch for broadband capability. Low thermal resistance package reduces junction temperature, extends life.

ABSOLUTE MAXIMUM RATINGS

Maximum Power Dissipation @ 25°C² 875 Watts

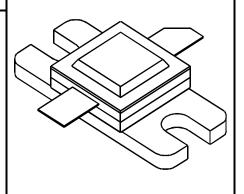
Maximum Voltage and Current

BVcesCollector to Base Voltage55 VoltsBVeboEmitter to Base Voltage4.0 VoltsIcCollector Current30 Amps

Maximum Temperatures

Storage Temperature $-65 \text{ to} + 200^{\circ}\text{C}$ Operating Junction Temperature $+200^{\circ}\text{C}$

CASE OUTLINE 55AW, STYLE 1



ELECTRICAL CHARACTERISTICS @ 25 °C

SYMBOL	CHARACTERISTICS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Pout Pin Pg η _c VSWR	Power Out Power Input Power Gain Collector Efficiency Load Mismatch Tolerance	$F = 960-1215 \text{ MHz}$ $Vcc = 50 \text{ Volts}$ $PW = 10 \mu\text{sec}$ $DF = 5\%$ $F = 1090 \text{ MHz}$	250 6.2	35	60 5:1	Watts Watts dB %

BVebo	Emitter to Base Breakdown	Ie = 20 mA	4.0		Volts
BVces	Collector to Emitter Breakdown	Ic = 25 mA	55		Volts
Cob	Capacitance Collector to Base	Vcb = 50 Volts			
$\mathbf{h}_{\mathbf{FE}}$	DC - Current Gain	Ic = 1 mA, Vce = 5 V	10		pF
θ j \mathbf{c}^2	Thermal Resistance			0.2	°C/W

Note 1: At rated output power and pulse conditions

2: At rated pulse conditions

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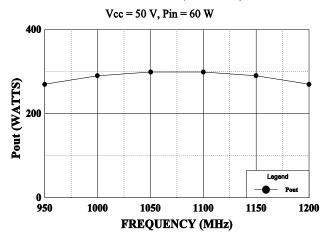
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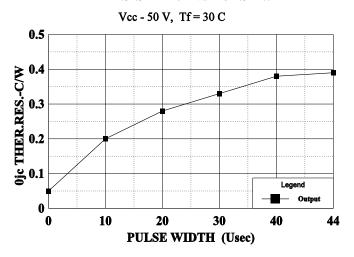


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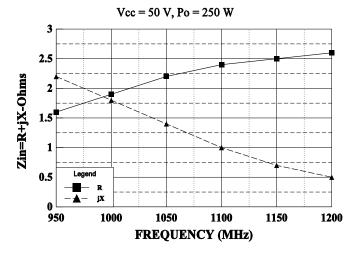
POWER OUTPUT (TYPICAL)



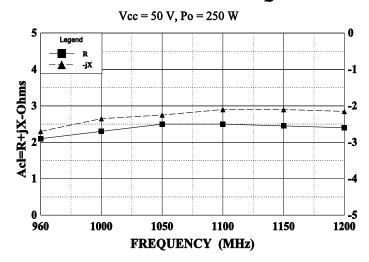
THERMAL RESISTANCE vs PULSE WIDTH



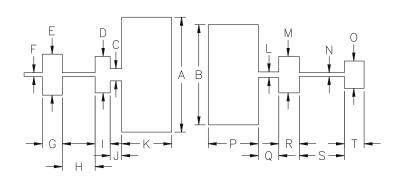
SERIES INPUT IMPEDANCE vs FREQUENCY



SERIES LOAD IMPEDANCE vs FREQUENCY

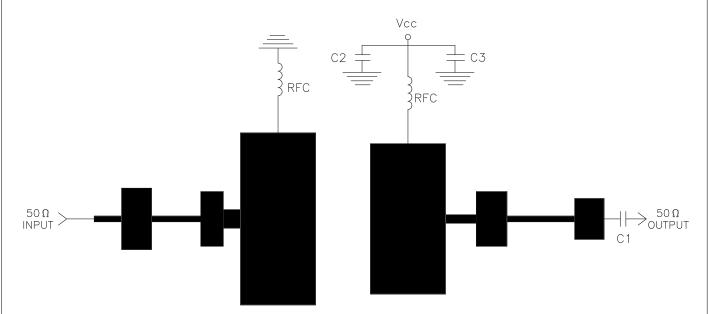






DIM	INCHES
Α	1.260
В	1.100
С	.135
D	.400
E	.450
F	.042
G	.220
Н	.360
1	.165
J	.125
K	.550
L	.062
М	.400
Ν	.042
0	.230
Р	.550
Q	.225
R	.225
S	.495
Т	.215

960-1215 MHz BROADBAND TEST AMPLIFIER



PCB = .020" TFE, 2 oz. CU. Type "GT" C1, C2 = 82pf Chip C3 = 250 MFD



cage OPJR2	DWG NO.	DMEG 250		REV $f A$	
	SCALE	1/1	SHEET		